



# PSA

**PASSIVE SYSTEM ALLIANCE**

— *One Vision, the strength of many* —

# WHAT IS PSA ?

*“An integrated electronics solution provider, **Passive System Alliance** is where we unite our strengths, technologies, and vision to overcome obstacles together as we climb toward new heights and achieve goals as one team.”*

*- PSA Chairman Yu-Heng Chiao*

# WALSIN GROUP



**Revenue** : Estimated US\$13B (2025)

**Market Cap** : Estimated US\$25.16B

**Listed Companies (TW+JP)** : 16

**Ranking** : Top 20 Group in TWSE

<b>Sector</b>	Industrial Materials, Energy Infrastructure, and High-end Manufacturing
<b>Products</b>	<ul style="list-style-type: none"> <li>• Wire &amp; Cables</li> <li>• Stainless Steel</li> <li>• Raw Materials for the above</li> </ul>
<b>Revenue</b>	Estimated US\$5.5B (2025)
<b>Est.</b>	1966



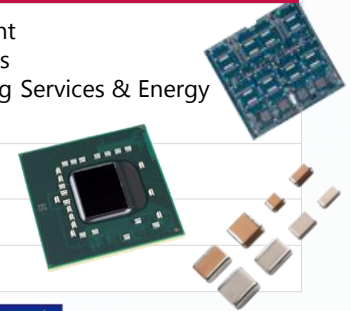
## winbond

<b>Sector</b>	Semiconductor Memory ICs
<b>Products</b>	<ul style="list-style-type: none"> <li>• Specialty DRAM</li> <li>• Serial NOR/NAND FLASH</li> <li>• Automotive-grade Memory</li> </ul>
<b>Revenue</b>	Estimated US\$2.84B (2025)
<b>Est.</b>	1986



# PSA

<b>Sectors</b>	<ul style="list-style-type: none"> <li>• Passive &amp; RF Component</li> <li>• PCB &amp; FPC Technologies</li> <li>• Electronic Manufacturing Services &amp; Energy</li> <li>• IC Packaging &amp; Testing</li> </ul>
<b>Products</b>	<i>See More</i> →
<b>Revenue</b>	Estimated US\$4.3B (2025)
<b>Est.</b>	1986



## HannStar

<b>Sector</b>	Display Panels & Touch Solutions
<b>Products</b>	<ul style="list-style-type: none"> <li>• TFT-LCD Panels</li> <li>• Display Modules</li> <li>• Touch Panel Solutions</li> </ul>
<b>Revenue</b>	Estimated US\$0.36B (2025)
<b>Est.</b>	1998



# PSA EXECUTIVE OVERVIEW



**2002**

Established



**11**

Listed Companies



**41,000+**

Employees



**60+**

Factories



**US\$4.3B**

2025 Global Revenues  
*(Estimated)*



**US\$7.3B**

2025 Market Cap  
*(Estimated)*



**US\$546M**

2025 Cash-Flow  
*(Estimated)*

# PSA SECTOR OVERVIEW

*Four core business sectors delivering integrated electronics solutions*

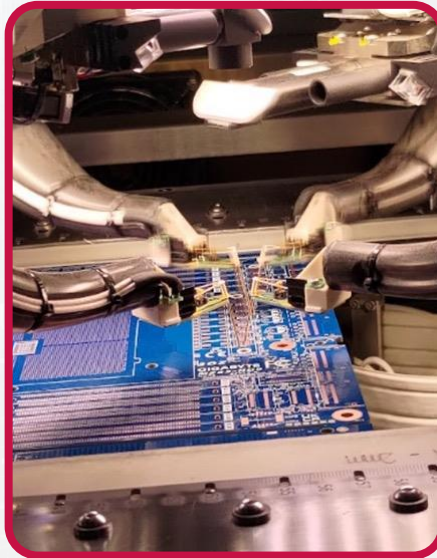
**01**

**Passive Components**



**02**

**PCB Technologies**



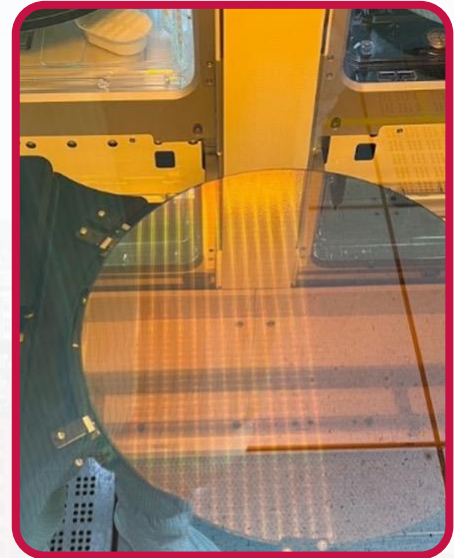
**03**

**EMS & Energy**



**04**

**IC Packaging**



# PSA GROUP MEMBERS

*Four core business sectors delivering integrated electronics solutions*

## Passive Components

Walsin Technology 2492.TW

Prosperity Dielectrics Co. 6173.TW

INPAQ Technology 6284.TW

Kamaya Electric

Nitsuko Electronics

Soshin Electric

Matsuo Electric 6969.JP

## PCB Technologies

Hannstar Board Corporation 5469.TW

Global Brands Manufacture 6191.TW

Career Technology 6153.TW

ELNA Printed Circuits

Lincstech

## EMS & Energy

Info-Tek Corporation 8183.TW

Global Brands Manufacture 6191.TW

Silitech Technology 3311.TW

FDK Corporation 6955.JP

## IC Packaging

Walton Technology 8110.TW

# PSA SECTOR OVERVIEW

Four core business sectors delivering integrated electronics solutions

## 01

### Passive Components

- **US\$1.3B** in 2025 Revenue
- **Top 2** in Global Supplier of **Chip Resistors**
- **Tier 1** Supplier of **MLCC**
- Leading Supplier of **RF Components & Modules**
- Fully Integrated **Materials, Manufacturing Processes, and Equipment Capabilities**

## 02

### PCB Technologies

- **US\$1.8B** in 2025 Revenue
- **12M sq.ft.** Monthly Rigid PCB Capacity
- **No.1** Supplier of Notebook PCBs
- **Top 9 PCB/FPC** Supplier Worldwide (Prismark 2024's)
- **200K+ sq. ft. Monthly** Capacity Dedicated to AI Infrastructure, Server, and Semiconductor Test PCBs (Probe Cards, HDI & mSAP)
- **#Dedicated AI+PCB supplier**

## 03

### EMS & Energy

- **US\$1B** in 2025 Revenue
- **100+ SMT** and Production Lines across Taiwan, China, and Malaysia
- **Tier 1** Supplier of Nickel–metal Hydride Batteries
- Top-tier Mid-scale **EMS Manufacturer**
- Proven Capabilities in Back-end Assembly, Testing, and Module Integration Services
- Strong Specialization in **BMS and Automotive Electronics**

## 04

### IC Packaging

- **US\$0.2B** in 2025 Revenue
- Tier 1 Key Supplier to US Mobile Device Supply Chain
- Strong Capabilities in **Back-end Semiconductor Processes**
- Vertically Integrated **IC Packaging and Testing operations**

PSA

# 佳邦科技股份有限公司

INPAQ TECHNOLOGY CO., LTD.

WE CONNECT & WE PROTECT WE ARE ONE

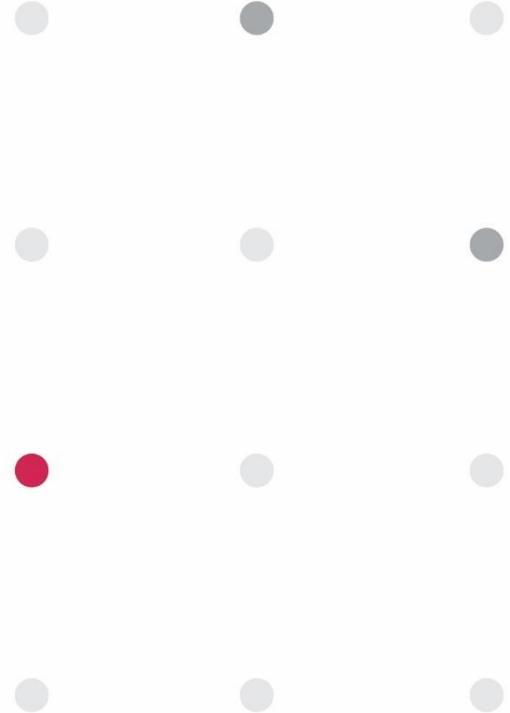


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PASSIVE SYSTEM ALLIANCE

PSA

PASSIVE SYSTEM ALLIANCE  
INPAQ TECHNOLOGY CO., LTD.  
WE CONNECT & WE PROTECT WE ARE ONE



# We are INPAQ



Chairman  
Anthony Chiao



CEO & President  
Eunice Chen



INPAQ Fact

CY2025 Sales

NT\$7,620 Millions

IPO

6284. TT TW

Capital

NT\$ 1,490 Millions

## Global Presence since 1998

2140<sup>↑</sup>

Global INPAQ  
People

5<sup>↑</sup>

Factories

## Innovation

24<sup>↑</sup>

Chambers

100<sup>↑</sup>

Intellectual  
Properties

210<sup>↑</sup>

RD  
Experts

## Customer & Service

24H<sup>↑</sup>

Global Support

100<sup>↑</sup>

Global Brands  
Customers

# Global INPAQ

Plant X5

Lab X24

Sales X7



## China

Location	Type	Detail
Suzhou	Plant Lab	Antenna, 5 Labs
Wuxi	Plant Lab	EMC/Power/Antenna, 2 Labs
Shenzhen	Lab Sales	Office, 3 Labs
Xi'an	Lab Sales	Office, 1 Lab
Shanghai	Sales	Office



## Malaysia

Location	Type	Detail
Malaysia	Plant	ESD/EMC/Power/Antenna

## Global Network

Location	Type	Detail
USA	Sales Dist	CA, NJ, MN
Japan	Lab Dist	Kanagawa ; Tokyo, Nagoya, Osaka
Korea	Dist	Seoul, Gyeonggido
Singapore	Dist	Paya Lebar
Australia	Dist	New South Wales
Europe	Sales Dist	Germany, Italy



## Taiwan

Location	Type	Detail
Miaoli	HQ Plant Lab Sales	ESD/EMC/Power/Antenna Plant I, II, III 10 Labs
Taichung	Plant	EMC
Taipei	Lab Sales	Office, 2 Labs

# INPAQ Malaysia Sdn. Bhd.

## Penang Expansion

Establishing a strategic manufacturing hub in Malaysia.  
Ready for Mass Production in 2026.

ADD: Prai Industrial Estate, 13600 Prai, Penang, Malaysia

### Location



### Plant View



### Key Timeline

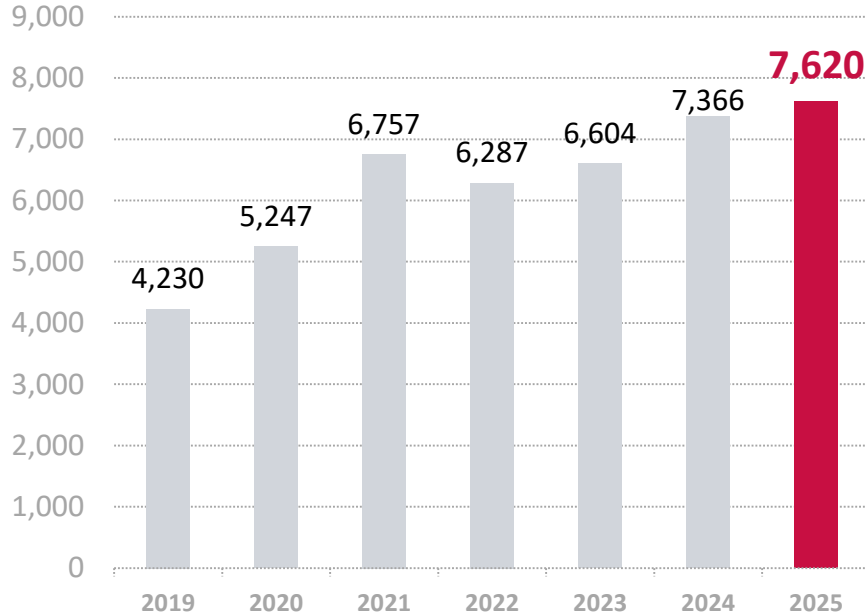
- 2025 June  
Plant Inauguration
- Target: 2026 March  
Quality (Auto) Certification  
ISO 9001 / IATF 16949 (LOC)  
Letter of Conformance
- Target: 2026 July  
EHS Certification  
ISO 14001 / ISO 45001

# INPAQ Sales Revenue & Business Segment

Financial Overview 2019-2025

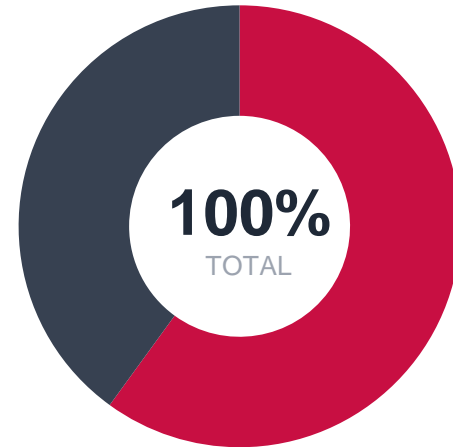
## Annual Revenue Trend

Unit: NT\$ Million



## Segment Breakdown

Revenue breakdown by product type



RF Antenna 60 %  
Passive Component 40 %

# INPAQ Quality System & Global Delivery Assurance

Delivering Global Reliability for INPAQ Products

## ◆ Int'l Certifications — Market-Proven Capabilities



- IATF 16949 / ISO 9001
  - ▶ Automotive & High-Reliability Quality
- QC 080000 (HSPM)
  - ▶ Material Compliance (RoHS/REACH)
- ISO 14001 (Env) / ISO 45001 (OH&S)

## ◆ Multi-Site Mgmt — Resilient & Secure Supply Chain



- Sites in Taiwan, China & Malaysia (Penang)
- Unified Std., Process & Inspection Mgmt.
- Flexible transfer to ensure Quality & LT
- Agile Production Capacity

Remark : Std. = Standard ; Mgmt. = Management

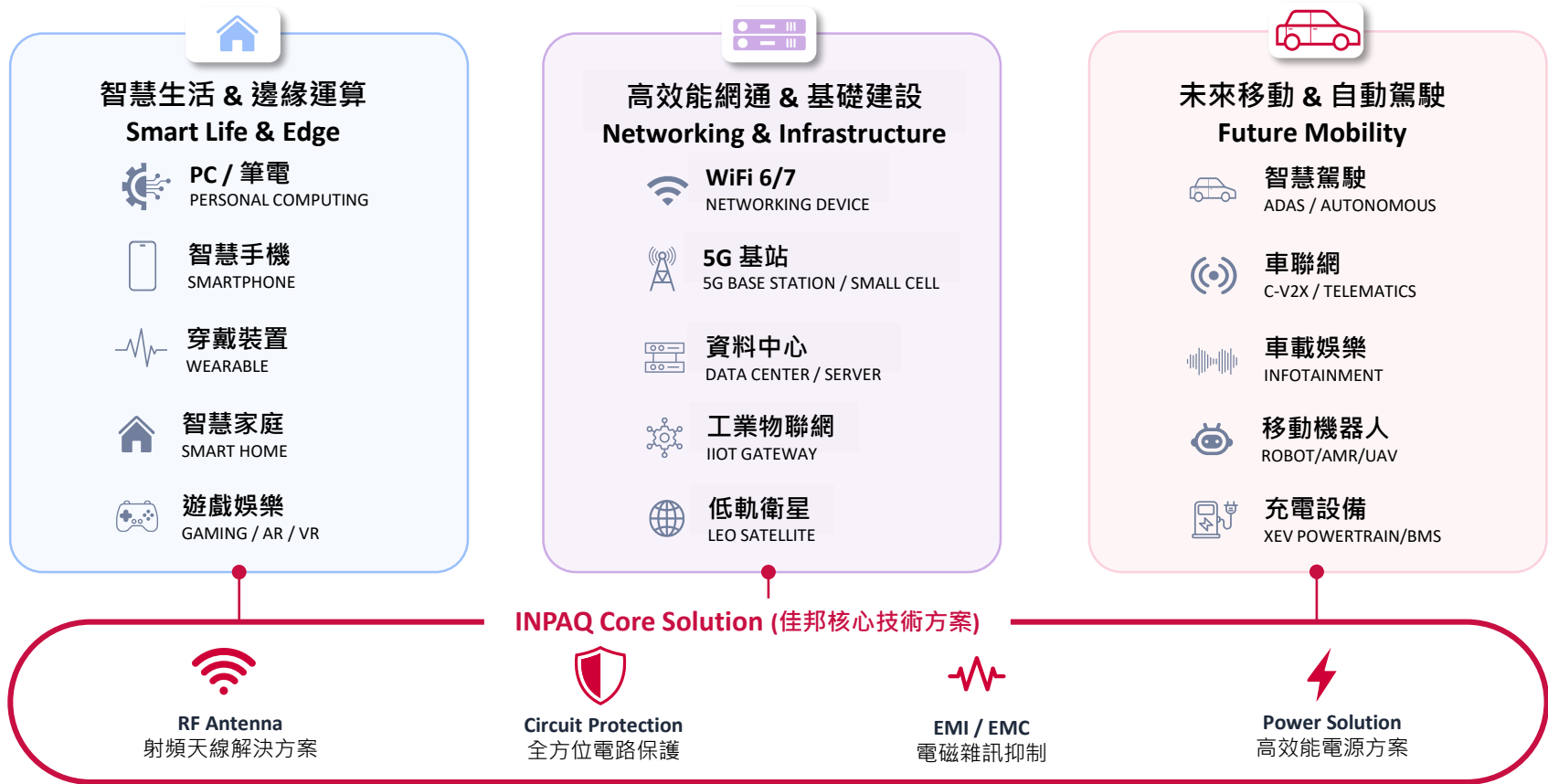
## ◆ System Implementation — Traceable & Verifiable Quality



- PLM / ISO-Web / ERP Integration
- E-Doc Management & Change Tracking
- Audit & Improvement Records
- Digital Quality Management

# INPAQ Integrated Application

## ● From Core Solutions to Future-Ready Markets



# INPAQ Global Market Leadership

Data From: In-house statistics

## CONNECT

### RF Antenna

#### TOP 1

Global Rank • GPS Patch Antenna

#### TOP 4

Global Rank • NB/PC Antenna

#### 1st

Chip Antenna in metal enclosure

## PROTECT

### Passive Component

#### TOP 1

Global Rank • Ultra-Low Cap ESD Suppressor

#### TOP 4

Global Rank • Mini Molding Power Inductor

#### TOP 4

Global Rank • RF Inductor



# INPAQ

## One Signal, One Journey



**RF Antenna**

Wireless Connectivity



**ESD Protection**

Electrostatic Discharge



**RF Inductor**

Impedance Matching



**EMI Filter**

Noise Suppression



**Power Inductor**

Power Efficiency

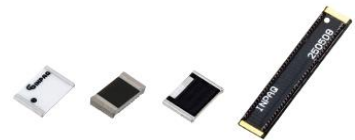
# INPAQ RF Antenna

## Internal On Board

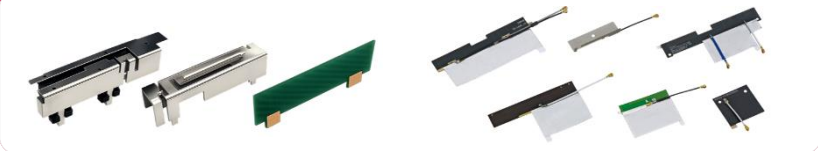
### Patch



### Chip



### Metal/PCB/FPCB



## Internal Structural

### Active GNSS



### LDS



## External & Outdoor

### GNSS



### Automotive combo



### Dipole



### DAS/CPE



## Module

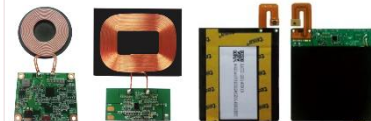
### GNSS module



### UWB module



### WPC module



### mmW module




# INPAQ Passive Component

## ESD/Surge Protection

### ESD Suppressor



**EGA (ESD Guard™)**   
Ceramic type  
low capacitance (0.2pF)



**TFE/TUE**  
Thin film type  
Ultra low capacitance  
(0.05~0.07pF)

### TVS Diode



**TVS\_CSP type**  
End-cap electrode




**TVS\_DFN type**   
Excellent ESD protection



**Power TVS**   
For power line

### Varistor




**MLVS P/L series**   
General surge protection



**MLVS H series**  
High surge ability



**MLVS HV series**   
High voltage application  
UL/cUL 1449 approved

## RF Inductor & EMI Filter

### RF Inductor



**Multilayer type** 



**Wire-wound type** 



**Air coil** 

### EMI filter



**Common mode choke**  
Multilayer type



**Common mode choke**  
Wire-wound type 



**Chip bead** 

## Power Inductor

### Power Inductor



**Mini-molding type** 



**Big-molding type** 



**NR-resin type** 



**Multilayer type**

# INPAQ Integrated Technology

## Innovation

### Material Technology

- Dielectric Ceramic
- Magnetic Ceramic
- Magnetic Alloy



## Competition

### Process Technology

- Multilayer
- Thick film
- Thin film
- LTCC
- Molding
- Wire-wound
- LDS
- LAP

## Advanced Design Service

### Analysis & Evaluation

- 3D simulation: CST, HFSS, Maxwell
- Circuit simulation: ADS, AWR, Designer
- Laboratory: 24 anechoic chambers

# Thank you

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